



Thin Bond Line, Low-Pressure Thermal Control for Advanced Devices

BERGQUIST® HI FLOW THF 5000UT from Henkel is a breakthrough in phase change thermal interface material (TIM) engineering, offering superior thermal performance. With thin bond lines and low thermal impedance at very low pressure (< 10 psi) and at higher pressure (> 35 psi), the formulation delivers excellent thermal capability, while minimizing stress. BERGQUIST® HI FLOW THF 5000UT is solid at room temperature but flows and fills the interface once it reaches its target temperature (45°C). Thermal conductivity as high as 8.5 W/m-K has been achieved, the material has good pump out resistance, and has demonstrated excellent reliability up to 150°C.

Applications

- > Cloud data center, 5G telecom infrastructure, industrial automation, and automotive applications
- › Any system that requires a thin bond line TIM with low thermal resistance with more stable performance and handling
- > Challenging ICs with complex designs, such as lidless multi-chip packages for advanced compute and networking applications

Benefits

- > Excellent and efficient heat dissipation through low thermal resistance
- > Market-leading performance at low pressure application (<10 psi)
- > Consistent performance across varying bond line thickness and pressure
- High reliability up to 150°C
- > No mess, simple integration
- > Sustainability, no burn-in required saves time and energy
- > Supply chain simplicity, pre-applied at heat sink supplier

Features

- > Optimized for lidless and multi-chip applications: 0.06°C-cm² /W at < 10 psi
- > Low thermal impedance: 0.04°C-cm²/W at 35 psi
- Excellent reliability: 1000 hours -40°C to 125°C / 85°C, 85% RH / 125°C / 150°C
- > Immediate effectiveness, no burn-in required for bond line pre-wetting
- Thin bond line at 25 μm (minimum)
- > Available in various thicknesses (8, 10, 12, and 16 mils)
- > Global supply with manufacturing in North America and Asia



Want to to know more about BERGQUIST® HI FLOW THF 5000UT?

Connect with our team: lndustrials-americas@henkel.com

Across the Board, Around the Globe.

henkel-adhesives.com/us/en/industries/ data-and-telecom-infrastructure

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